

# ADHESION MEASUREMENT OF THIN FILMS, THICK FILMS, AND BULK COATINGS

K. L. MITTAL, *editor*



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**AMERICAN SOCIETY FOR TESTING AND MATERIALS**

# ADHESION MEASUREMENT OF THIN FILMS, THICK FILMS, AND BULK COATINGS

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# Foreword

The symposium on Adhesion Measurement of Thin Films, Thick Films, and Bulk Coatings was held at the headquarters of the American Society for Testing and Materials, Philadelphia, Pa., 2-4 Nov. 1976. The ASTM Publications Committee sponsored the symposium. K. L. Mittal, IBM Corporation, presided as symposium chairman and editor of this publication.

## Related ASTM Publications

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**Surface Analysis Techniques for Metallurgical Applications, STP 596  
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